

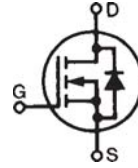
HiPerRF™

Power MOSFETs

F-Class: MegaHertz Switching

IXFH12N50F IXFT12N50F

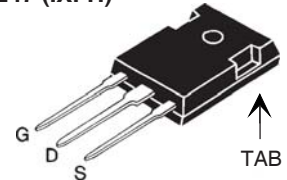
N-Channel Enhancement Mode
Avalanche Rated, Low Q_g , Low
Intrinsic R_g , High dV/dt , Low t_{rr}



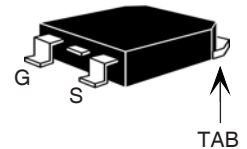
$$\begin{aligned} V_{DSS} &= 500V \\ I_{D25} &= 12A \\ R_{DS(on)} &\leq 400m\Omega \\ t_{rr} &\leq 250ns \end{aligned}$$

Symbol	Test Conditions	Maximum Ratings	
V_{DSS}	$T_J = 25^\circ\text{C}$ to 150°C	500	V
V_{DGR}	$T_J = 25^\circ\text{C}$ to 150°C , $R_{GS} = 1M\Omega$	500	V
V_{GSS}	Continuous	± 20	V
V_{GSM}	Transient	± 30	V
I_{D25}	$T_C = 25^\circ\text{C}$	12	A
I_{DM}	$T_C = 25^\circ\text{C}$, Pulse Width Limited by T_{JM}	48	A
I_{AR}	$T_C = 25^\circ\text{C}$	12	A
E_{AS}	$T_C = 25^\circ\text{C}$	300	mJ
dV/dt	$I_S \leq I_{DM}$, $di/dt \leq 100A/\mu s$, $V_{DD} \leq V_{DSS}$ $T_J \leq 150^\circ\text{C}$, $R_G = 2\Omega$	20	V/ns
P_D	$T_C = 25^\circ\text{C}$	180	W
T_J		-55 ... +150	$^\circ\text{C}$
T_{JM}		150	$^\circ\text{C}$
T_{stg}		-55 ... +150	$^\circ\text{C}$
T_L	Maximum Lead Temperature for Soldering	300	$^\circ\text{C}$
T_{SOLD}	Plastic Body for 10s	260	$^\circ\text{C}$
M_d	Mounting Torque (TO-247)	1.13/10	Nm/lb.in.
Weight	TO-247	6	g
	TO-268	4	g

TO-247 (IXFH)



TO-268 (IXFT)



G = Gate D = Drain
S = Source TAB = Drain

Features

- RF capable MOSFETs
- Double metal process for low gate resistance
- Low $R_{DS(on)}$ DHMOS™ process
- Rugged polysilicon gate cell structure
- Unclamped Inductive Switching (UIS) rated
- Low package inductance
- Fast intrinsic rectifier

Applications

- DC-DC converters
- Switched-mode and resonant-mode power supplies, >500kHz switching
- DC choppers
- 13.5 MHz industrial applications
- Pulse generation
- Laser drivers
- RF amplifiers

Advantages

- Space savings
- High power density

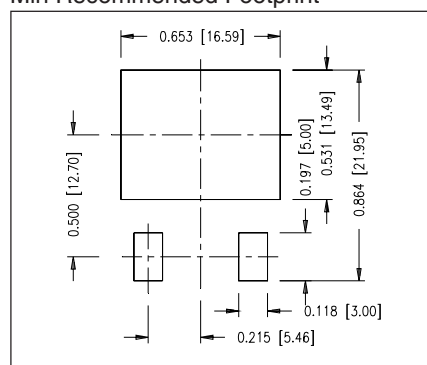
Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
BV_{DSS}	$V_{GS} = 0V$, $I_D = 250\mu A$	500		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 2.5mA$	3.0		5.5 V
I_{GSS}	$V_{GS} = \pm 20V$, $V_{DS} = 0V$			± 100 nA
I_{DSS}	$V_{DS} = 0.8 \cdot V_{DSS}$			50 μA
	$V_{GS} = 0V$ $T_J = 125^\circ\text{C}$			1.5 mA
$R_{DS(on)}$	$V_{GS} = 10V$, $I_D = 0.5 \cdot I_{D25}$, Note 1			400 m Ω

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$ Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
g_{fs}	$V_{DS} = 10\text{V}$, $I_D = 0.5 \cdot I_{D25}$, Note	6	10	S
C_{iss}	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1\text{MHz}$		1870	pF
C_{oss}			290	pF
C_{rss}			90	pF
$t_{d(on)}$	Resistive Switching Times $V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}$ $R_G = 4.7\Omega$ (External)		11	ns
t_r			14	ns
$t_{d(off)}$			28	ns
t_f			8	ns
$Q_{g(on)}$	$V_{GS} = 10\text{V}$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_D = 0.5 \cdot I_{D25}$		54	nC
Q_{gs}			18	nC
Q_{gd}			25	nC
R_{thJC}	(TO-247)			0.65°C/W
R_{thCS}		0.21		$^\circ\text{C/W}$

Source-Drain Diode		Characteristic Values		
$T_J = 25^\circ\text{C}$ Unless Otherwise Specified)		Min.	Typ.	Max.
I_S	$V_{GS} = 0\text{V}$			12 A
I_{SM}	Repetitive, Pulse Width Limited by T_{JM}			48 A
V_{SD}	$I_F = I_S$, $V_{GS} = 0\text{V}$, Note 1			1.5 V
t_{rr}	$I_F = 12\text{A}$, $-di/dt = 100\text{A}/\mu\text{s}$ $V_R = 100\text{V}$, $V_{GS} = 0\text{V}$			250 ns
Q_{RM}			0.8	μC
I_{RM}			6.5	A

Note: 1. Pulse test, $t \leq 300 \mu\text{s}$, duty cycle $d \leq 2\%$

Min Recommended Footprint



TO-247 (IXFH) Outline

